

# Digital FET, N-Channel FDV301N, FDV301N-F169

## **General Description**

This N-Channel logic level enhancement mode field effect transistor is produced using **onsemi's** proprietary, high cell density, DMOS technology. This very high density process is especially tailored to minimize on-state resistance. This device has been designed especially for low voltage applications as a replacement for digital transistors. Since bias resistors are not required, this one N-channel FET can replace several different digital transistors, with different bias resistor values.

#### **Features**

- 25 V, 0.22 A Continuous, 0.5 A Peak
  - $R_{DS(on)} = 5 \Omega @ V_{GS} = 2.7 V$
  - $R_{DS(on)} = 4 \Omega @ V_{GS} = 4.5 V$
- Very Low Level Gate Drive Requirements Allowing Direct Operation in 3 V Circuits. V<sub>GS(th)</sub> < 1.06 V</li>
- Gate-Source Zener for ESD Ruggedness. > 6 kV Human Body Model
- Replace Multiple NPN Digital Transistors with One DMOS FET
- This Device is Pb-Free and Halide Free

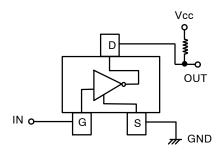
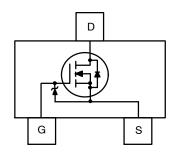


Figure 1. Inverter Application





SOT-23 CASE 318-08

#### **MARKING DIAGRAM**



&E = Designates Space &Y = Binary Calendar Year Coding Scheme

301 = Specific Device Code

&G = Date Code

## **ORDERING INFORMATION**

Device	Package	Shipping <sup>†</sup>
FDV301N, FDV301N-F169	SOT-23-3 (Pb-Free, Halide-Free)	3000 / Tape & Reel

<sup>†</sup>For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

# ABSOLUTE MAXIMUM RATINGS $T_A$ = $25^{\circ}C$ unless otherwise noted.

Symbol	Parameter	FDV301N	Unit
V <sub>DSS</sub> , V <sub>CC</sub>	Drain-Source Voltage, Power Supply Voltage	25	V
V <sub>GSS</sub> , V <sub>I</sub>	Gate-Source Voltage, V <sub>IN</sub>	8	V
I <sub>D</sub> , I <sub>O</sub>	Drain/Output Current - Continuous	0.22	Α
		0.5	
P <sub>D</sub>	Maximum Power Dissipation	0.35	W
T <sub>J</sub> , T <sub>STG</sub>	Operating and Storage Temperature Range	-55 to 150	°C
ESD	Electrostatic Discharge Rating MIL–STD–883D Human Body Model (100 pF/1500 $\Omega$ )	6.0	kV

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

## THERMAL CHARACTERISTICS T<sub>A</sub> = 25°C unless otherwise noted.

Symbol	Parameter	Value	Unit
$R_{ heta JA}$	Thermal Resistance, Junction-to-Ambient	357	°C/W

## **INVERTER ELECTRICAL CHARACTERISTICS** $T_A = 25^{\circ}C$ unless otherwise noted.

Symbol	Parameter	Test Conditions	Min	Тур	Max	Unit
I <sub>O(off)</sub>	Zero Input Voltage Output Current	V <sub>CC</sub> = 20 V, V <sub>I</sub> = 0 V	-	-	1	μΑ
V <sub>I(off)</sub>	Input Voltage	$V_{CC} = 5 \text{ V}, I_{O} = 10 \mu\text{A}$	-	_	0.5	V
V <sub>I(on)</sub>		$V_O = 0.3 \text{ V}, I_O = 0.005 \text{ A}$	1	_	_	
R <sub>O(on)</sub>	Output to Ground Resistance	V <sub>I</sub> = 2.7 V, I <sub>O</sub> = 0.2 A	-	4	5	Ω

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

## **ELECTRICAL CHARACTERISTICS** $T_A = 25^{\circ}C$ unless otherwise noted.

Symbol	Parameter	Test Conditions	Min	Тур	Max	Unit
OFF CHARACTERISTICS						
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$	25	-	_	V
$\Delta BV_{DSS}/\Delta T_{J}$	Breakdown Voltage Temp. Coefficient	I <sub>D</sub> = 250 μA, Referenced to 25°C	-	25	-	mV/°C
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	V <sub>DS</sub> = 20 V, V <sub>GS</sub> = 0 V	-	-	1	μΑ
		V <sub>DS</sub> = 20 V, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 55°C	-	-	10	
I <sub>GSS</sub>	Gate - Body Leakage Current	V <sub>GS</sub> = 8 V, V <sub>DS</sub> = 0 V	-	-	100	nA
ON CHARACTERISTICS						
$\Delta V_{GS(th)}/\Delta T_J$	Gate Threshold Voltage Temp. Coefficient	I <sub>D</sub> = 250 μA, Referenced to 25°C	_	-2.1	-	mV/°C
V <sub>GS(th)</sub>	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_D = 250 \mu A$	0.70	0.85	1.06	V
R <sub>DS(on)</sub>	Static Drain-Source On-Resistance	V <sub>GS</sub> = 2.7 V, I <sub>D</sub> = 0.2 A	-	3.8	5	Ω
		$V_{GS} = 2.7 \text{ V}, I_D = 0.2 \text{ A}, T_J = 125^{\circ}\text{C}$	-	6.3	9	
		V <sub>GS</sub> = 4.5 V, I <sub>D</sub> = 0.4 A	-	3.1	4	
I <sub>D(on)</sub>	On-State Drain Current	V <sub>GS</sub> = 2.7 V, V <sub>DS</sub> = 5 V	0.2	-	-	Α
9FS	Forward Transconductance	V <sub>DS</sub> = 5 V, I <sub>D</sub> = 0.4 A	-	0.2	_	S

## ELECTRICAL CHARACTERISTICS T<sub>A</sub> = 25°C unless otherwise noted. (continued)

Symbol	Parameter	Test Conditions	Min	Тур	Max	Unit
YNAMIC CH	ARACTERISTICS					
C <sub>iss</sub>	Input Capacitance	V <sub>DS</sub> = 10 V, V <sub>GS</sub> = 0 V, f = 1.0 MHz		9.5	_	pF
C <sub>oss</sub>	Output Capacitance		-	6	_	
C <sub>rss</sub>	Reverse Transfer Capacitance		-	1.3	-	
WITCHING (	CHARACTERISTICS (Note 1)					
t <sub>D(on)</sub>	Turn - On Delay Time	$V_{DD} = 6 \text{ V}, I_{D} = 0.5 \text{ A}, V_{GS} = 4.5 \text{ V},$ $R_{GEN} = 50 \Omega$	-	3.2	8	ns
t <sub>r</sub>	Turn – On Rise Time		-	6	15	
t <sub>D(off)</sub>	Turn – Off Delay Time		-	3.5	8	
t <sub>f</sub>	Turn – Off Fall Time		-	3.5	8	
Qg	Total Gate Charge	$V_{DS} = 5 \text{ V}, I_D = 0.2 \text{ A}, V_{GS} = 4.5 \text{ V}$	-	0.49	0.7	nC
Q <sub>gs</sub>	Gate-Source Charge		-	0.22	_	
$Q_{gd}$	Gate-Drain Charge		-	0.07		
RAIN-SOUF	RCE DIODE CHARACTERISTICS AND M	AXIMUM RATINGS				_
Is	Maximum Continuous Drain-Source Di	Maximum Continuous Drain-Source Diode Forward Current		-	0.29	Α
V <sub>SD</sub>	Drain-Source Diode Forward Voltage	V <sub>GS</sub> = 0 V, I <sub>S</sub> = 0.29 A (Note 1)	-	0.8	1.2	V

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

1. Pulse Test: Pulse Width ≤ 300 μs, Duty Cycle ≤ 2.0%.

### TYPICAL CHARACTERISTICS

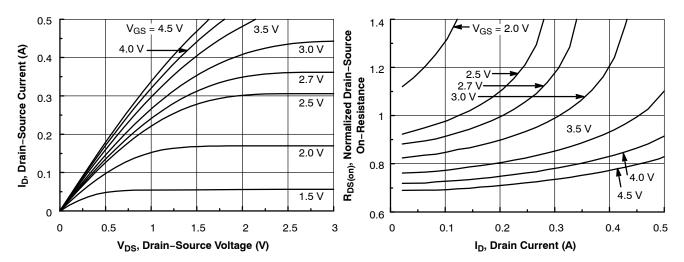
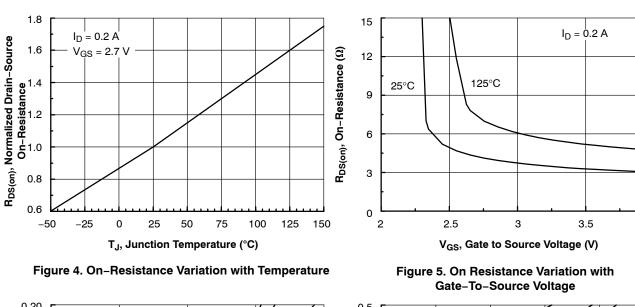


Figure 2. On-Region Characteristics

Figure 3. On-Resistance Variation with Drain Current and Gate Voltage

## TYPICAL PERFORMANCE CHARACTERISTICS (continued)



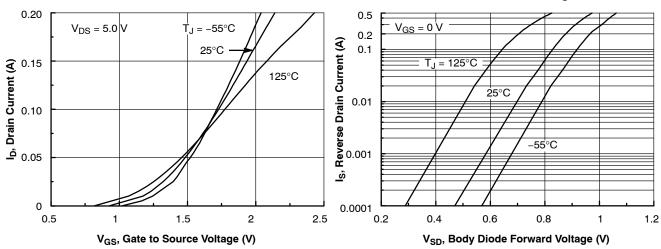


Figure 6. Transfer Characteristics

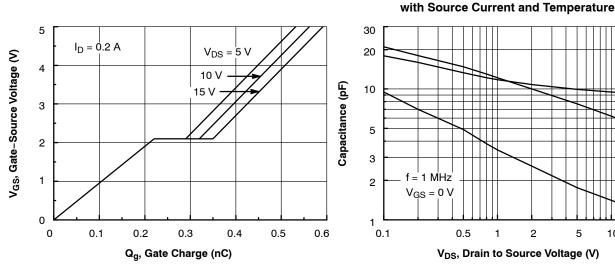


Figure 8. Gate Charge Characteristics

Figure 9. Capacitance Characteristics

Figure 7. Body Diode Forward Voltage Variation

 $C_{\underline{iss}}$ 

Coss

 $C_{\text{rss}}$ 

25

10

## TYPICAL PERFORMANCE CHARACTERISTICS (continued)

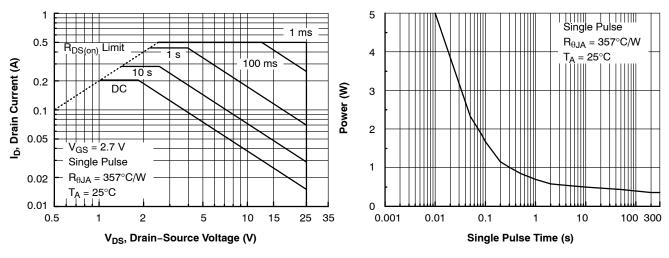


Figure 10. Maximum Safe Operating Area

Figure 11. Single Pulse Maximum Power Dissipation

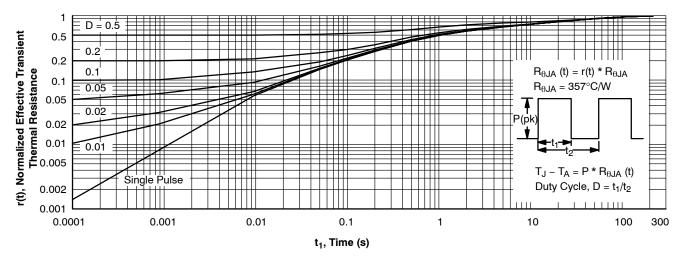


Figure 12. Transient Thermal Response Curve

**MILLIMETERS** 

MIN

0.89

0.01

0.37

0.08

2.80

1.20

1.78

0.30

0.35

2.10

O°

NOM

1.00

0.06

0.44

0.14

2.90

1.30

1.90

0.43

0.54

2.40

\_\_\_





## SOT-23 (TO-236) 2.90x1.30x1.00 1.90P **CASE 318 ISSUE AU**

**DATE 14 AUG 2024** 

MAX

1.11

0.10

0.50

0.20

3.04

1.40

2.04

0.55

0.69

2.64

10°

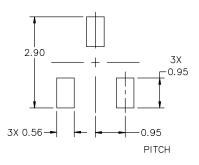




DETAIL "A" Scale 3:1







#### NOTES:

DIM

Α

Α1

b

С

D

Ε

е L

L1

HE

Τ

- DIMENSIONING AND TOLERANCING 1. PER ASME Y14.5M, 2018. CONTROLLING DIMENSIONS:
- MILLIMETERS.
- MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF THE
- BASE MATERIAL.
  DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS.

## **GENERIC MARKING DIAGRAM\***



XXX = Specific Device Code

= Date Code

= Pb-Free Package

## RECOMMENDED MOUNTING FOOTPRINT

\* For additional information on our Pb-Free strategy and soldering details, please download the onsemi Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

### **STYLES ON PAGE 2**

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<sup>\*</sup>This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "=", may or may not be present. Some products may not follow the Generic Marking.

## SOT-23 (TO-236) 2.90x1.30x1.00 1.90P CASE 318 ISSUE AU

DATE 14 AUG 2024

STYLE 1 THRU 5: CANCELLED	STYLE 6: PIN 1. BASE 2. EMITTER 3. COLLECTOR		NODE D CONNECTION ATHODE	
STYLE 9: PIN 1. ANODE 2. ANODE 3. CATHODE	STYLE 10: PIN 1. DRAIN 2. SOURCE 3. GATE	STYLE 11:         STYLE 12:           PIN 1. ANODE         PIN 1. CA           2. CATHODE         2. CA           3. CATHODE-ANODE         3. AN	ATHODE PIN 1. SOURCE ATHODE 2. DRAIN	STYLE 14: PIN 1. CATHODE 2. GATE 3. ANODE
STYLE 15: PIN 1. GATE 2. CATHODE 3. ANODE	STYLE 16: PIN 1. ANODE 2. CATHODE 3. CATHODE			STYLE 20: PIN 1. CATHODE 2. ANODE 3. GATE
STYLE 21: PIN 1. GATE 2. SOURCE 3. DRAIN	STYLE 22: PIN 1. RETURN 2. OUTPUT 3. INPUT	STYLE 23:         STYLE 24:           PIN 1. ANODE         PIN 1. GAT           2. ANODE         2. DR/           3. CATHODE         3. SOU	TE PIN 1. ANODE AIN 2. CATHODE	STYLE 26: PIN 1. CATHODE 2. ANODE 3. NO CONNECTION
STYLE 27: PIN 1. CATHODE 2. CATHODE 3. CATHODE	STYLE 28: PIN 1. ANODE 2. ANODE 3. ANODE			

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